

METHODS OF PACKAGING SEMICONDUCTOR WAFERS BY MOLDING A
PACKING BAG ABOUT A CARRYING DEVICE THAT CONTAINS THE
SEMICONDUCTOR WAFERS

Abstract of the Disclosure

Semiconductor wafers are packed by providing a carrying device that holds one or more semiconductor wafers. The carrying device is inserted into a packing bag and the packing bag is molded using at least a portion of the external form of the carrying device as a guide such that a portion of the packing bag substantially
5 conforms to the portion of the external form of the carrying device. Thus, wafers may be packaged without using a vacuum while still inhibiting contamination from particles and the formation of haze on the surface of the wafers.

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